



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-08-05
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH15RQ06DY	B1DK*U66Q2AI	A	3068	2020-08-05
	Amount	UoM	Unit type	ST ECOPACK Grade
	1860	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
Not Applicable	Not Applicable	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00637534	



Package Designator	Size	Nbr of instances	Shape	
SIP	10.00,9.10,4.50	2	Through hole	
Comment	DO 220			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.16	die - leadframe	85
Lead	2.74	soft solder	1475

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.74	Soft solder	1475
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	2.744	Soft solder	954767

Material Composition Declaration :						Mfr Item Name	B1DK*U66Q2AI					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	4.452	mg	supplier	die	Silicon(Si)	7440-21-3		4.213	mg	946317	2264
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.125	mg	28077	67
				supplier	metallisation	Gold(Au)	7440-57-5		0.007	mg	1572	4
				supplier	metallisation	Nicke(Ni)	7440-02-0		0.034	mg	7637	18
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.002	mg	449	1
				supplier	passivation	Silicon oxide	7631-86-9		0.071	mg	15948	38
Leadframe	M-004 Copper and its alloys	1184.449	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8		1182.774	mg	998585	635900
				supplier	alloy & coating	Nicke(Ni)	7440-02-0		0.124	mg	105	67
				supplier	alloy & coating	Iron(Fe)	7439-89-6		1.184	mg	1000	637
				supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8		0.355	mg	300	191
				supplier	alloy & coating	Phosphorus metal	7723-14-0		0.012	mg	10	6
Soft solder	Solder	2.874	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	2.744	mg	954767	1475
				supplier	solder	Silver(Ag)	7440-22-4		0.072	mg	25052	39
				supplier	solder	Tin(Sn)	7440-31-5		0.058	mg	20181	31
Bonding wires	M-003 Aluminum and its alloys	4.925	mg	supplier	wire	Aluminium (Al)	7429-90-5		4.925	mg	1000000	2648
Encapsulation	M-011 Other inorganic materials	659.059	mg	supplier	mold compound	Silica vitreous	60676-86-0		461.341	mg	700000	248033
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		102.154	mg	155000	54922
				supplier	mold compound	Quartz	14808-60-7		32.953	mg	50000	17717
				supplier	mold compound	Phenol resin	9003-35-4		39.544	mg	60000	21260
				supplier	mold compound	Metal hydroxide	proprietary		19.772	mg	30000	10630
				supplier	mold compound	Carbon black	1333-86-4		3.295	mg	5000	1772
connections coating	Solder	4.241	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.241	mg	1000000	2280